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L4 ANSWER 7 OF 12 HCA COPYRIGHT 2002 ACS

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PATENT NO.	KIND	DATE	APPLICATION NO.	DATE
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JP 11279511	A2	19991012	JP 1998-87480	19980331
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TI Electrically conductive adhesives for circuit joints

AB The title adhesives, useful for elec. bonding circuit electrodes (e.g.,  
of

Au, Ag, Sn, Pt) by applying and pressing together, comprise (a) hardeners capable of generating free radicals by heating (e.g., Percure HO), (b) OH-contg. resins with mol. wt. >10,000 (e.g., PKHC), (c) radical polymerizable compds. (e.g., 80MFA, o-allyl phenol, Light Ester P 2M),

(d) allyl methacrylate, and optionally (e) acrylic rubber and/or (f) elec. conductive particles (e.g., Ni- and Au-plated polystyrene particles).

L4 ANSWER 8 OF 12 HCA COPYRIGHT 2002 ACS

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PATENT NO.	KIND	DATE	APPLICATION NO.	DATE
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JP 11279513	A2	19991012	JP 1998-87482	19980331
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TI Electrically conductive adhesives for circuit joints

AB The title adhesives, useful for elec. bonding circuit electrodes (e.g.,  
of

Au, Ag, Sn, Pt) by applying and pressing together, comprise (a) hardeners capable of generating free radicals by heating (e.g., Percure HO), (b) OH-contg. resins with mol. wt. >10,000 (e.g., PKHC), (c) radical polymerizable compds. (e.g., 80MFA, o-allyl phenol, Light Ester P 2M),

(d) o-allyl phenol, and optionally (e) acrylic rubber and/or (f) elec. conductive particles (e.g., Ni- and Au-plated polystyrene particles).